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**INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND
METHOD OF MANUFACTURING THE SAME**

Appl. No. : 10/755,042 Confirmation No. 8665
Applicant : Jin-Yuan Lee,
Mou-Shiung Lin,
Ching-Cheng Huang
Filed : January 9, 2004
TC/A.U. : 2815
Examiner : Fenty, Jesse A
Docket No. : MEGP0004USA1
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

RESPONSE TO FINAL OFFICE ACTION AND ADVISORY OFFICE ACTION

5 Sir:

In response to the Final Office Action mailed Jan. 4, 2007 and Advisory Office Action mailed Apr. 9, 2007, please consider the remarks as follows:

Remarks/Arguments begin on page 2 of this paper.